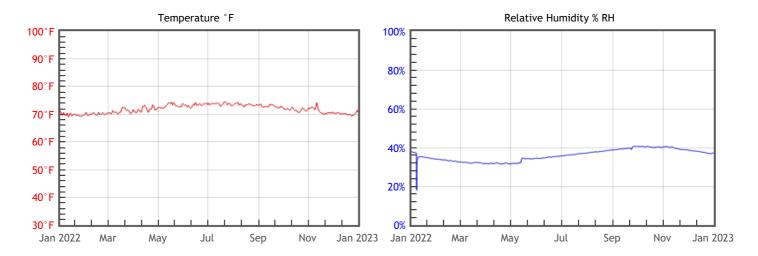
Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 49	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	GOOD % DC = 0.35 % EMC min = 6.4 % EMC max = 7.7	Minimal risk of physical damage to most hygroscopic materials such as paintings, rare books and furniture.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 7.7	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Statistics

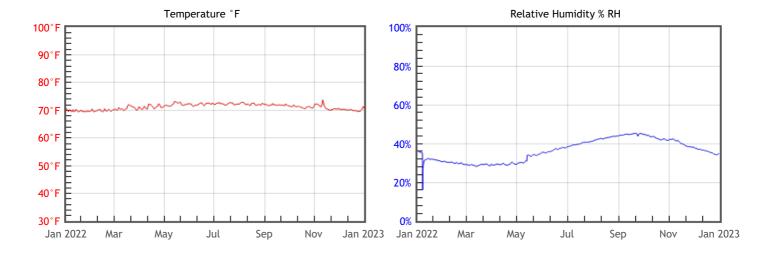
Temperature		Relative H	Relative Humidity		Dew Point	
T°F Mean	71.9	%RH Mean	36	DP°F Mean	43.4	
T°F Median	72	%RH Median	36	DP°F Median	43.8	
T°F Stdev	1.5	%RH Stdev	3	DP°F Stdev	2.7	
T°F Min	68.9	%RH Min	18	DP°F Min	24.2	
T°F Max	75.5	%RH Max	41	DP°F Max	49.4	

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 50	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 0.69 % EMC min = 6 % EMC max = 8.4	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.4	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Statistics

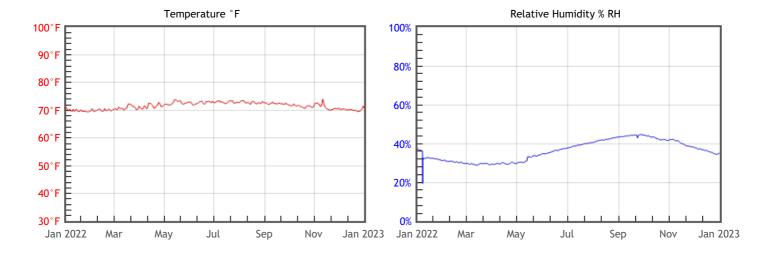
Temperature		Relative Humidity		Dew Point	
T°F Mean	71.2	%RH Mean	36	DP°F Mean	42.9
T°F Median	71.4	%RH Median	37	DP°F Median	43.1
T°F Stdev	1	%RH Stdev	6	DP°F Stdev	4.6
T°F Min	69.2	%RH Min	16	DP°F Min	21.2
T°F Max	74.3	%RH Max	46	DP°F Max	50.5

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 48	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 0.64 % EMC min = 6 % EMC max = 8.3	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.3	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	71.6	%RH Mean	36	DP°F Mean	43.2
T°F Median	71.8	%RH Median	36	DP°F Median	43.2
T°F Stdev	1.2	%RH Stdev	5	DP°F Stdev	4.3
T°F Min	69.2	%RH Min	19	DP°F Min	26.1
T°F Max	74.6	%RH Max	45	DP°F Max	50.5